

# PHOTO TRIAC COUPLERS PS3641,PS3641L,PS3642,PS3642L

## PHOTO TRIAC OUTPUT TYPE 5-PIN PHOTOCOUPLER

#### **DESCRIPTION**

The PS3641, PS3642 and PS3641L, PS3642L are optically coupled isolators containing a GaAs light emitting diode and photo triac.

The PS3641, PS3642 are in a plastic DIP (Dual In-line Package) and the PS3641L, PS3642L are lead bending type (Gull-wing) for surface mounting.

#### **FEATURES**

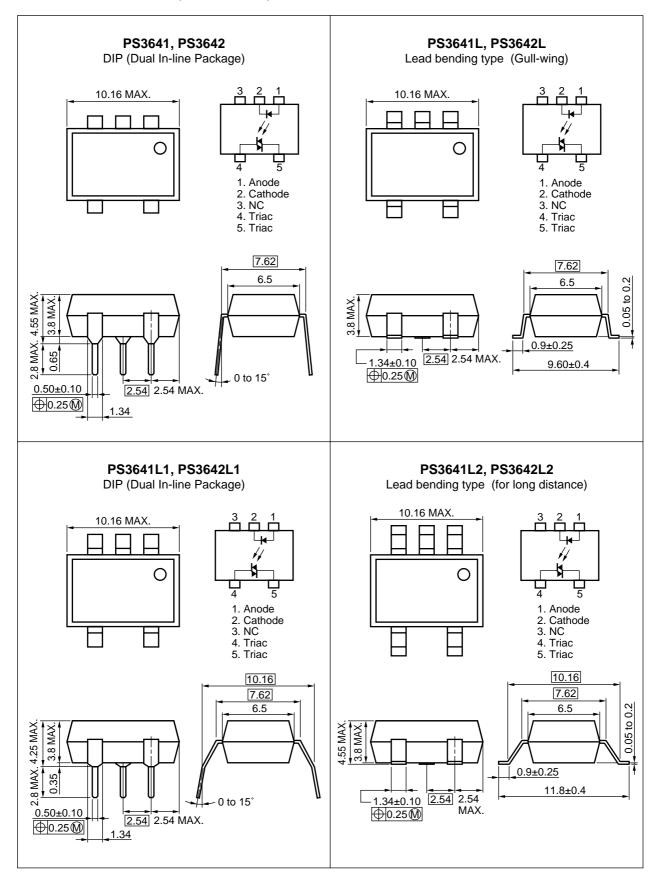
- High critical rate of rise of off-state voltage ( $dV/dt = 500 V/\mu s TYP$ .)
- High repetitive peak off-state voltage (PS3641, PS3641L: VDRM = 600 V MIN.)
   (PS3642, PS3642L: VDRM = 400 V MIN.)
- High Isolation voltage (BV = 5 000 Vr.m.s. MIN.)
- ★ Taping product name (PS3641L-E3, E4, PS3642L-E3, E4)
  - Clearance distance of pin to opposite type (PS3641L1, PS3641L2, PS3642L1, PS3642L2)

### **APPLICATIONS**

- · For triggering triac
- · Controller for miniature motor

The information in this document is subject to change without notice.

### **PACKAGE DIMENSIONS (in millimeters)**



### ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings		Unit
			PS3641, PS3641L	PS3642, PS3642L	
Diode	Forward Current (DC)	lF	8	mA	
	Reverse Voltage	VR	6.0 1.5 150		V
	Power Dissipation Derating	∆P₀/°C			mW/°C
	Power Dissipation	Po			mW
	Peak Forward Current <sup>⁴1</sup>	IFP			Α
Detector	Repetitive Peak Off-state Voltage	VDRM	600	400	V
	RMS On-state Current <sup>2</sup>	IT (RMS)	Iтsм 0.5		mA
	Peak 1 Cycle Surge On Current <sup>3</sup>	Ітѕм			Α
	Power Dissipation Derating	∆Pc/°C			mW/°C
	Power Dissipation	Pc	150		mW
Isolation Voltage <sup>*4</sup>		BV	5 000		Vr.m.s.
Operating Ambient Temperature		TA	-40 to +100		°C
Storage Temperature		T <sub>stg</sub>	-55 to +125		°C

- \*1 PW = 100  $\mu$ s, Duty Cycle = 1 %
- ★ \*2 Current for operation of this device differs depending on conditions such as load, operating temperature, and supply voltage
  - \*3 Sine Wave f = 50 Hz
  - \*4 AC voltage for 1 minute at T<sub>A</sub> = 25 °C, RH = 60 % between input and output

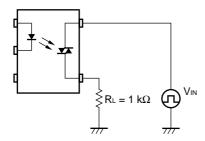
#### **RECOMMENDED OPERATING CONDITIONS**

Parameter		Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage PS3641		Vac			240	Vac
	PS3642				120	
Forward Current		lF	15	20	30	mA
Operating Ambient Temperature		TA	-25		+85	°C

### ELECTRICAL CHARACTERISTICS (TA = 25 °C)

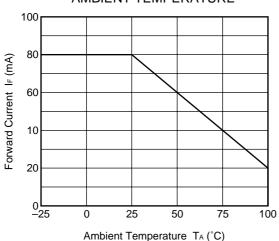
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.1	1.4	V
	Reverse Current	<b>I</b> R	VR = 5 V			5	μΑ
	Terminal Capacitance	Ct	V = 0 V, f = 1 MHz		30		pF
Photo Triac	Peak Off-state Current	IDRM	VDRM = ±Rated			100	nA
	Peak On-state Voltage	Vтм	Iтм = ±Rated		2.5	3.0	V
	Holding Current	lн			0.8		mA
	Critical Rate of Rise of Off-state Voltage*1	dV/dt	$V_{IN} = \pm 1/\sqrt{2}$ Rated	200	500		V/μs
Coupled	Trigger Input Current	İFT	V <sub>TM</sub> = ±6 V		6	10	mA
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1 kV <sub>DC</sub>	10 <sup>11</sup>			Ω
	Isolation Capacitance	Cı-o	V = 0 V, f = 1 MHz		0.4		pF

\*1 Test circuit for critical rate of rise of off-state voltage

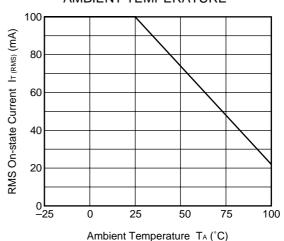


#### TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)

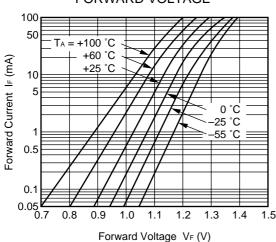




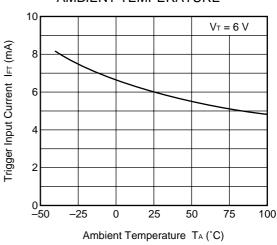
### RMS ON-STATE CURRENT vs. AMBIENT TEMPERATURE



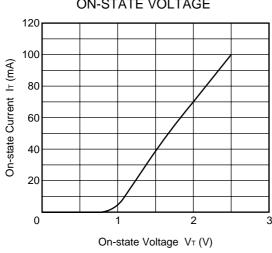
### FORWARD CURRENT vs. FORWARD VOLTAGE



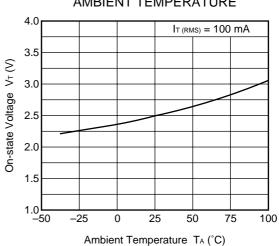
TRIGGER INPUT CURRENT vs. AMBIENT TEMPERATURE



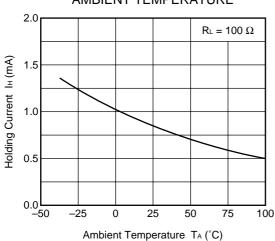
### ON-STATE CURRENT vs. ON-STATE VOLTAGE



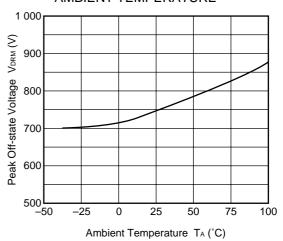
### ON-STATE VOLTAGE vs. AMBIENT TEMPERATURE



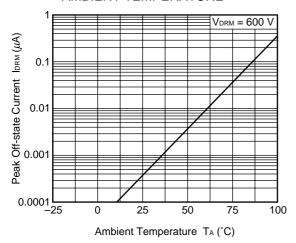
### HOLDING CURRENT vs. AMBIENT TEMPERATURE



### PEAK OFF-STATE VOLTAGE vs. AMBIENT TEMPERATURE



### PEAK OFF-STATE CURRENT vs. AMBIENT TEMPERATURE

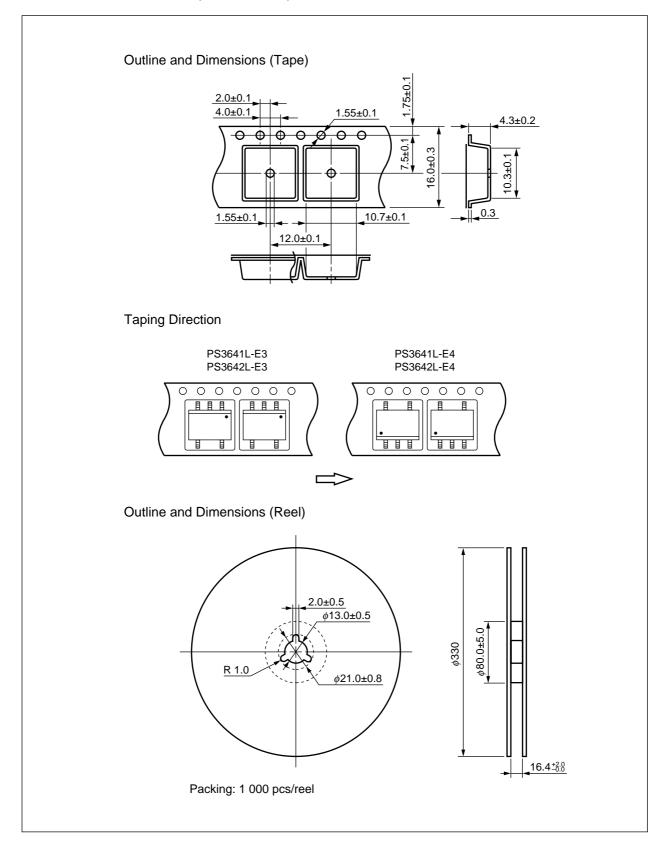


### PRECAUTION FOR USER

- 1. Mount all pin for improvement heat sink.
- 2. Be sure to connect a circuit for surge absorbent.

An appropriate circuit must be chosen according to the load (for CR, chose its constant). This must be carefully done especially for an inductive load.

### \* TAPING SPECIFICATIONS (in millimeters)



### RECOMMENDED SOLDERING CONDITIONS

### (1) Infrared reflow soldering

• Peak reflow temperature 235 °C (package surface temperature)

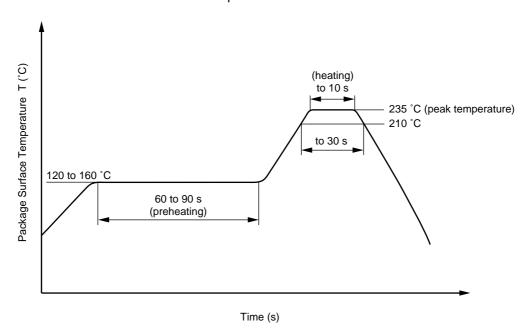
• Time of temperature higher than 210 °C 30 seconds or less

Number of reflows
 Three

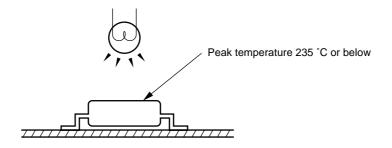
• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt % is recommended.)

#### Recommended Temperature Profile of Infrared Reflow



Caution Please avoid to removed the residual flux by water after the first reflow processes.



### (2) Dip soldering

• Temperature 260 °C or below (molten solder temperature)

• Time 10 seconds or less

• Number of times One

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of

0.2 Wt % is recommended.)

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#### **CAUTION**

Within this device there exists GaAs (Gallium Arsenide) material which is a harmful substance if ingested. Please do not under any circumstances break the hermetic seal.

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Anti-radioactive design is not implemented in this product.